



## WETS D'15 Workshop

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# **PD Diagnostics on MV cables**

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**PD** detection

**PD** measurement

**PD** localization

types of testing





#### Introduction – what are partial discharges?

How to measure?

#### localization:

- **TDR time domain reflectometry**
- sTDR statistical TDR

#### overview of technologies in the market



#### What is partial discharge ?

> Partial discharge (PD) is a localized dielectric breakdown of a small portion of a solid or liquid electrical insulation system under high voltage stress.



> Definition from IEC 60270 Specification:

Localized electrical discharge that only partially bridges the insulation between conductors and which can or cannot occur adjacent to a conductor.



### What are partial discharges?

Partial discharge:

- > Local electrical stress in the insulation or on the surface of the insulation
- > Always generates electromagnetic signals
- > Often accompanied by an emission of sound, light, heat and chemical reactions







#### **Breakdown of cable and termination**









photo: IPH Berlin

## **Electrical treeing in PE**







photo: IPH Berlin







![](_page_10_Picture_3.jpeg)

![](_page_10_Picture_4.jpeg)

![](_page_11_Picture_1.jpeg)

![](_page_11_Picture_2.jpeg)

![](_page_12_Picture_0.jpeg)

![](_page_12_Picture_1.jpeg)

video: IPH Berlin

![](_page_12_Picture_3.jpeg)

# How to measure?

![](_page_13_Picture_1.jpeg)

#### **Charge – How to measure?**

> Time Domain Integration  $q = \int_{t_1}^{t_2} i(t)dt = \frac{1}{R} \int_{t_1}^{t_2} u(t)dt$ 

![](_page_14_Figure_2.jpeg)

![](_page_14_Picture_3.jpeg)

### **Analog PD measurement systems**

![](_page_15_Figure_1.jpeg)

![](_page_15_Picture_2.jpeg)

### "Digital" PD measurement systems

![](_page_16_Figure_1.jpeg)

![](_page_16_Picture_2.jpeg)

# "Digital PD measurement system with digital filtering

![](_page_17_Figure_1.jpeg)

![](_page_17_Picture_2.jpeg)

#### **Types of PD**

- > Internal PD
  - > Void discharges, "electrical treeing"

![](_page_18_Picture_3.jpeg)

#### > External PD

- > Corona
- > Surface discharges

![](_page_18_Picture_7.jpeg)

![](_page_18_Picture_8.jpeg)

![](_page_18_Figure_9.jpeg)

![](_page_18_Picture_10.jpeg)

#### **External PD**

![](_page_19_Picture_1.jpeg)

Surface discharge

![](_page_19_Picture_3.jpeg)

Corona discharge

![](_page_19_Picture_5.jpeg)

#### **Internal PD**

![](_page_20_Figure_1.jpeg)

![](_page_20_Figure_2.jpeg)

![](_page_20_Figure_3.jpeg)

![](_page_20_Picture_4.jpeg)

#### **PD** classification

![](_page_21_Figure_1.jpeg)

Semicon layer protrusion (stress concentration at the tip)

Void (field strength doubling)

![](_page_21_Picture_4.jpeg)

#### Phase resolved partial discharge PRPD

PRPD correlation between PD pulses and voltage phase PD nature might be identified

![](_page_22_Figure_2.jpeg)

![](_page_22_Picture_3.jpeg)

#### Phase resolved partial discharge – PRPD

> How is a PRPD created?

![](_page_23_Figure_2.jpeg)

#### Further ways of PD analysis – Trend

![](_page_24_Figure_1.jpeg)

PD repetition rate vs. time

![](_page_24_Figure_3.jpeg)

Applied voltage vs. time

![](_page_24_Figure_5.jpeg)

PD repetition rate vs. applied voltage

![](_page_24_Figure_7.jpeg)

![](_page_24_Picture_8.jpeg)

#### Further ways of PD analysis – 3CFRD (3 Center Frequency Ratio Diagram)

#### > Pulse Shape Analysis: 3CFRD or Time/Frequency map

![](_page_25_Figure_2.jpeg)

#### Influence of inverse gating on external disturbances

![](_page_26_Figure_1.jpeg)

#### External disturbance

![](_page_26_Figure_3.jpeg)

![](_page_26_Figure_4.jpeg)

![](_page_26_Figure_5.jpeg)

![](_page_26_Figure_6.jpeg)

![](_page_26_Figure_7.jpeg)

![](_page_26_Picture_8.jpeg)

# Localization

![](_page_27_Picture_1.jpeg)

### **TDR – Time domain reflectometry**

- > A single PD pulse on an expanded test objects (cable) causes traveling waves in both directions
- > Pulses reaching the far cable end will be reflected
- > The reflected pulse will also be measured at the near end
- > The time delay of these 2 pulses depends on the PD fault position

![](_page_28_Figure_5.jpeg)

![](_page_28_Picture_6.jpeg)

### **TDR Curves for calibration and for PD**

- > Calibration
  - > equal distances between echos (partial reflections from joints possible)

#### > PD

> typically 2 different time distances

![](_page_29_Figure_5.jpeg)

![](_page_29_Picture_6.jpeg)

## **Calculation of fault position**

![](_page_30_Figure_1.jpeg)

,

#### PD fault position from

>

Far End 
$$l_{fault} = v_{PD} \cdot \frac{\Delta t}{2}$$

> Near End 
$$l_{fault} = L - v_{PD} \cdot \frac{\Delta t}{2}$$

![](_page_30_Picture_5.jpeg)

#### **PD** propagation speed

If v is unknown it can be found during calibration

- > if cable length is known
- > if only a single type of cable is tested

![](_page_31_Figure_4.jpeg)

![](_page_31_Picture_5.jpeg)

## **Travelling speeds and capacities in specific cable types**

Cable type	travelling speed in m/μs	Typical capacity in nF/km For conductor cross sections in mm <sup>2</sup> :						
		120	240	500	630	1200	1600	2500
XLPE 10kV	154-160	350	450	610	630	-	-	-
XLPE 20kV	164-170	240	300	400	-	-	-	-
XLPE 30kV	170-176	160	210	280	-	-	-	-
XLPE 60kV	174-176	-	-	-	236	-	-	-
XLPE 110kV	174-176	-	121	163	177	271	301	378
XLPE 150kV	~181	-	-	-	-	225	-	-
XLPE 220kV		-	106	143	155	236	260	294
XLPE 400kV		-	-	-	119	171	188	226
EPR 10kV	130-134	~300	500	-	-	-	-	-

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### **STDR – Statistical time domain reflectometry**

- > A single PD pulse on an expanded test objects (cable) causes traveling waves in both directions
- > Pulses will be reflected in the far cable end but partly also on every joint

![](_page_33_Figure_3.jpeg)

Assumption – Joints: 80% signal transmission; 20% signal reflection

![](_page_33_Picture_5.jpeg)

#### **STDR – Statistical time domain reflectometry**

- > Specific impulses are correlated to all measured impulses
- > The results of this correlation
  - > time difference between impulses
  - > relative amplitude of the correlated impulse
  - are drawn into the STDR histogram

![](_page_34_Figure_6.jpeg)

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# overview of technologies in the market

![](_page_35_Picture_1.jpeg)

#### technologies in the market

![](_page_36_Figure_1.jpeg)

![](_page_37_Figure_0.jpeg)

![](_page_38_Picture_0.jpeg)

![](_page_38_Figure_1.jpeg)

![](_page_38_Picture_2.jpeg)

#### **Cosinus rectangle - CosRec**

![](_page_39_Figure_1.jpeg)

![](_page_39_Picture_2.jpeg)

#### **CosRec – Zoom on falling slope**

![](_page_40_Figure_1.jpeg)

![](_page_40_Picture_2.jpeg)

#### **CosRec – Zoom on falling slope**

![](_page_41_Figure_1.jpeg)

![](_page_41_Picture_2.jpeg)

## **CosRec – PD only in slopes**

![](_page_42_Figure_1.jpeg)

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![](_page_43_Picture_0.jpeg)

![](_page_43_Figure_1.jpeg)

source: http://hvgrid-tech.com

![](_page_43_Picture_3.jpeg)

#### standards

IEC60885-3

IEC 60840

IEC 60502-2

IEEE 400 documents (.1, .2, .3, .4, .5)

CENELEC HD620 S1

**CIGRE** guides

![](_page_44_Picture_7.jpeg)

![](_page_45_Picture_0.jpeg)

![](_page_45_Picture_1.jpeg)